



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP7104ALUP/2YD-0L	Yellow (GaAsP/GaP)	Yellow Diffused	8	15	40°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	IF=20mA
C	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
IR	Reverse Current	Yellow		10	uA	VR=5V

Notes:

1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

Parameter	Yellow	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating Temperature	-40°C To +85°C	
Storage Temperature	-40°C To +85°C	

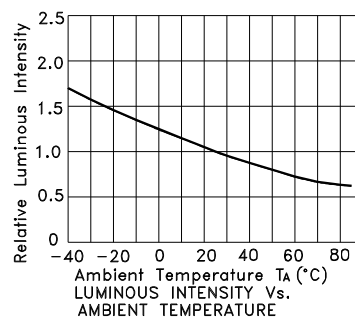
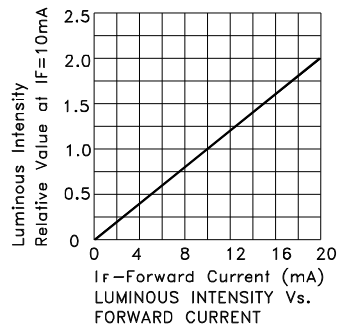
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



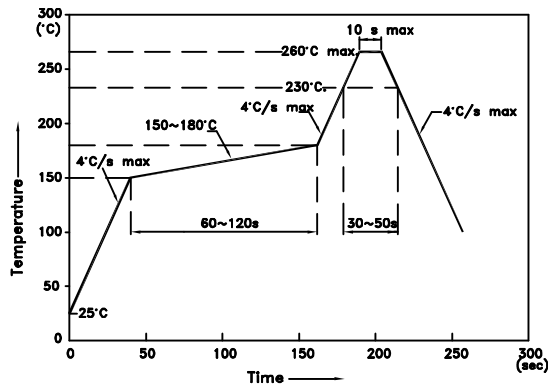
**Yellow**

**WP7104ALUP/2YD-0L**



## WP7104ALUP/2YD-0L

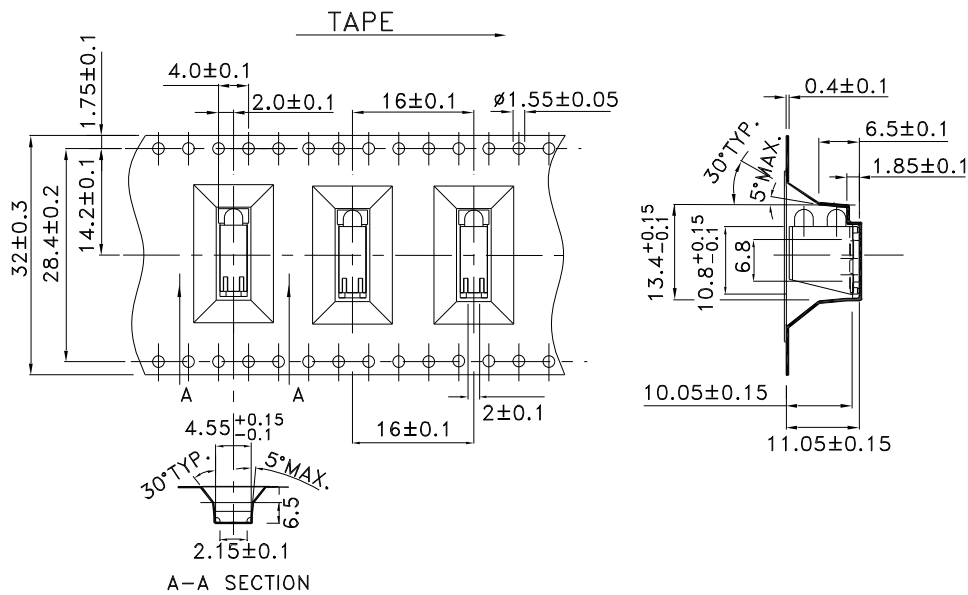
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

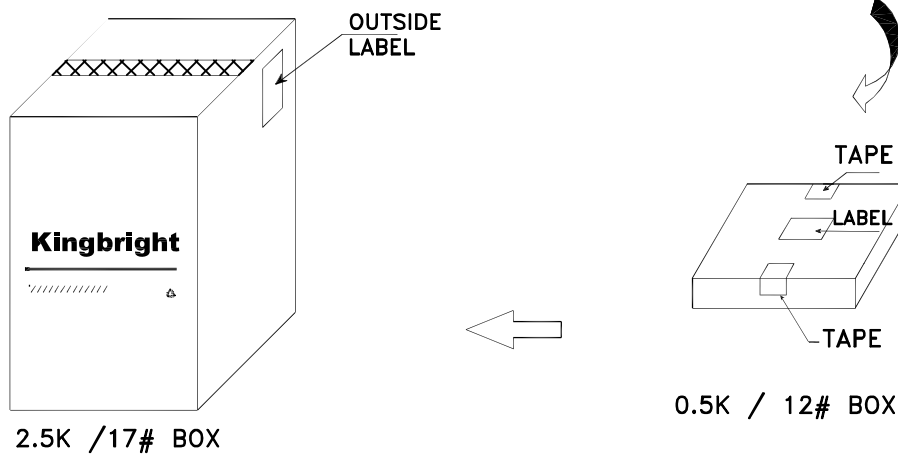
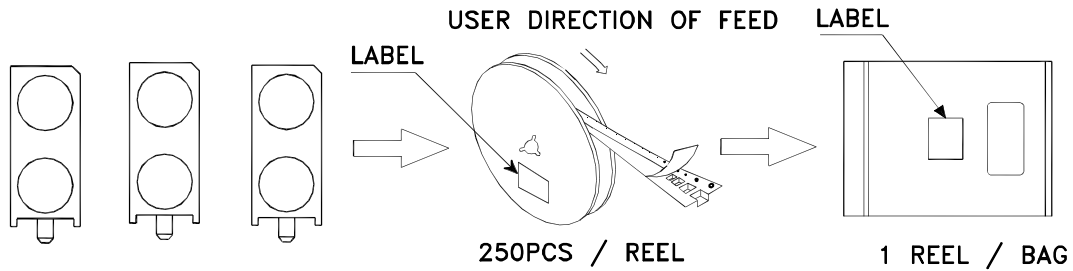
1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. No more than once.

### Tape Dimensions (Units : mm)



**PACKING & LABEL SPECIFICATIONS**

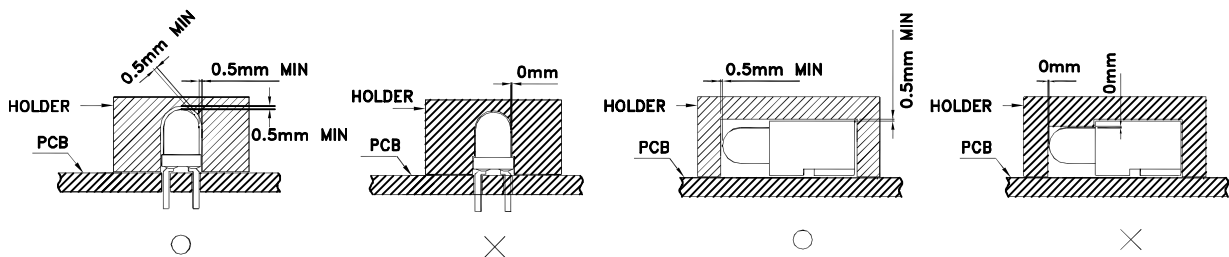
**WP7104ALUP/2YD-0L**



<h2 style="margin: 0;">Kingbright</h2>	
P/NO: WP7104ALUPxxx	
QTY: 250 pcs	Q.C.
S/N: XXXX	<div style="border: 1px solid black; border-radius: 50%; padding: 5px; display: inline-block;">             Q C              XX-XX-XXXX              PASSED           </div>
CODE: XXX	
LOT NO:	
 <small>xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx</small>	
RoHS Compliant	

## PRECAUTIONS

1. A moisture barrier bag (MBB) containing LEDs shall be kept in an environment with temperature below 40°C and humidity below 90% RH. A MBB shall be kept sealed until the LEDs contained in that bag are to be used immediately. Storage in an environment with temperature 5~30°C and humidity below 60% RH.
2. After a MBB has been opened, all LEDs contained in that bag shall complete soldering process within according to the conditions listed on the Kingbright MBB.
3. If the 10% spot of a humidity indicator card (HIC) indicates wet, LEDs shall be baked according to the conditions listed on the Kingbright MBB.
4. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



5. The tip of the soldering iron should never touch the lens epoxy.
6. After soldering, allow at least three minutes for the component to cool to room temperature before further operations.
7. If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.